Series 505 PLCC-to-PGA JEDEC
Type 0.050 [1.27] Pitch Adapter

FEATURES
- Convert surface mount PLCC packages to a PGA footprint
- Pin polarization option also available
- Consult factory for Panelized Form or for mounting of consigned chips

GENERAL SPECIFICATIONS
- ADAPTER BODY: FR-4, 0.062 [1.58] thick, with 1-oz. min. Cu traces
- PADS: hot-air solder leveled
- PINS: Brass 360 1/2-hard per UNS C36000 ASTM-B16-00
- PIN PLATING: 200μ [5.08μ] Sn/Pb 93/7 ASTM B579-73 over 100μ [2.54μ] Ni per ASE AMS-QQ-N-290 or 10μ [0.25μ] Au
- OPERATING TEMPERATURE: 221°F [105°C]

MOUNTING CONSIDERATIONS
- SUGGESTED PCB HOLE SIZE: 0.028 ±0.003 [0.71 ±0.08] dia
- STANDARD: will plug into PGA socket

ORDERING INFORMATION
XX-505-11 X-P
Optional Panelized Version
Pin Plating
0 = Sn (standard)
1 = Au

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS

CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. NOTE: Aries reserves the right to change product general specifications without notice.